

AMENDMENTS TO THE CLAIMS

The following is a complete, marked up listing of revised claims with a status identifier in parentheses, underlined text indicating insertions, and strikethrough and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. – 58. (Cancelled).

59. (Currently Amended) A chemical mechanical polishing (CMP) table having a monitoring function for monitoring a CMP process in-situ, the CMP table comprising:

a polishing pad including an in-situ window area that is thinner than the polishing pad adjacent to the in-situ window area; and

a platen attached to a ~~an opposite~~ side of the polishing pad opposite to ~~[[on]]~~ a polishing side~~[[,]]~~; wherein

the in-situ window area is composed of the same material layer as the polishing pad adjacent to the in-situ window area, and the platen has a hole which is vertically aligned with the in-situ window area, and

the platen has a platen window made of a transparent material in the hole of the platen to provide a void between the in-situ window area and the platen window.

60. (Previously Presented) The CMP table according to claim 59, wherein the in-situ window area has a thickness of 1.0 to 2.0 mm.

61. (Previously Presented) The CMP table according to claim 59, wherein the polishing pad is made of at least one of syndiotactic 1,2-polybutadiene, polyurethane, and PBD.

62. (Canceled)

63. (Currently Amended) The CMP table according to claim ~~[[62]]~~ 59, wherein the transparent material is at least one of polycarbonate, polyethylene terephthalate glycol, polypropylene, 2-aryl glycol carbonate, quartz, and glass.

64. (Currently Amended) The CMP table according to claim ~~[[62]]~~ 59, wherein the platen window is flush with the platen.

65. (Currently Amended) ~~The CMP table according to claim 62,~~ A chemical mechanical polishing (CMP) table having a monitoring function for monitoring a CMP process in-situ, the CMP table comprising:

a polishing pad including an in-situ window area that is thinner than the polishing pad adjacent to the in-situ window area; and

a platen attached to a side of the polishing pad opposite to a polishing side; wherein

the in-situ window area is composed of the same material layer as the polishing pad adjacent to the in-situ window area, and the platen has a hole which is vertically aligned with the in-situ window area,

the platen has a platen window made of a transparent material in the hole of the platen, the hole separating the in-situ window area and the platen window, and

[[wherein]] the platen window protrudes into the hole toward the in-situ window area from the platen to reduce the void.

66. (Currently Amended) A chemical mechanical polishing (CMP) table having a monitoring function for monitoring a CMP process in-situ, the CMP table comprising:

a polishing pad including an in-situ window area that is thinner than the polishing pad adjacent to the in-situ window area; and

a platen attached a side of the polishing pad opposite to a polishing side; wherein

the in-situ window area is composed of the same material layer as the polishing pad adjacent to the in-situ window area, and the platen has a hole which is vertically aligned with the in-situ window area,

the platen has a platen window made of a transparent material in the hole of the platen, and

~~The CMP table according to claim 62, wherein~~ the platen window protrudes from the platen to fill ~~[[the]]~~ a void between the platen window and the in-situ window area.

67. (Currently Amended) ~~The CMP table according to claim 62~~ A chemical mechanical polishing (CMP) table having a monitoring function for monitoring a CMP process in-situ, the CMP table comprising:

a polishing pad including an in-situ window area that is thinner than the polishing pad adjacent to the in-situ window area;

a platen attached to a side of the polishing pad opposite to a polishing side; and

further comprising a transparent supporting layer arranged between the in-situ window area and the platen; ~~in the void~~ wherein

the in-situ window area is composed of the same material layer as the polishing pad adjacent to the in-situ window area, and the platen has a hole which is vertically aligned with the in-situ window area,

the platen has a platen window made of a transparent material in the hole of the platen, the hole separating the in-situ window area and the platen window.

68. (Previously Presented) The CMP table according to claim 67, wherein the platen window protrudes from the platen and the transparent supporting layer is recessed from the polishing pad.

69. (Previously Presented) The CMP table according to claim 67, wherein the platen window is recessed from the platen and the transparent supporting layer protrudes from the polishing pad.

70. (Currently Amended) The CMP table according to claim 67, wherein the ~~void is filled with~~ the transparent supporting layer fills a space between the in-situ window area and the platen.